

### Features

- Low on-resistance
- High-speed switching
- Drive circuits can be simple
- Parallel use is easy
- ESD protected gate up to 1kV HBM

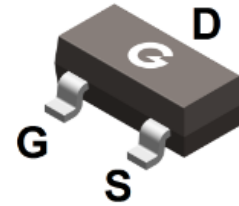
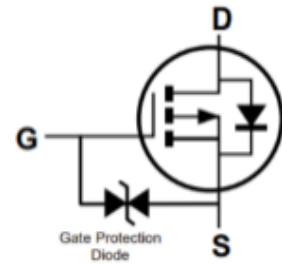
HF

### Typical Applications

- P-channel enhancement mode effect transistor
- Switching application

### Mechanical Data

- Case: SOT-23
- Molding Compound: UL Flammability Classification Rating 94V-0
- Terminals: Matte tin-plated leads; solderability-per MIL-STD-202, Method 208



SOT-23

### Ordering Information

Part Number	Package	Shipping Quantity	Marking Code
2N7001K	SOT-23	3000 pcs / Tape & Reel	7001K

### Maximum Ratings (@ T<sub>A</sub> = 25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DSS</sub>	-60	V
Gate -Source Voltage	V <sub>GSS</sub>	±20	V
Continuous Drain Current (T <sub>C</sub> = 25°C)	I <sub>D</sub>	-0.3	A
Continuous Drain Current (T <sub>A</sub> = 25°C) *1		-0.2	A
Continuous Drain Current (T <sub>A</sub> = 25°C) *1		-0.16	A
Pulsed Drain Current (t <sub>p</sub> = 10μs, T <sub>A</sub> = 25°C)	I <sub>DM</sub>	-1	A
Single Pulse Avalanche Energy *3	E <sub>AS</sub>	0.3	mJ
Power Dissipation (T <sub>A</sub> = 25°C) *1	P <sub>D</sub>	0.36	W
Operating Junction Temperature Range	T <sub>J</sub>	-55 ~ +150	°C
Storage Temperature Range	T <sub>STG</sub>	-55 ~ +150	°C

### Thermal Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal Resistance Junction-to-Air <sup>*1</sup>	R <sub>θJA</sub>	-	330	347	°C/W
Thermal Resistance Junction-to-Case <sup>*1</sup>	R <sub>θJC</sub>	-	185	208	°C/W
Thermal Resistance Junction-to-Lead <sup>*1</sup>	R <sub>θJL</sub>	-	145	175	°C/W

### Electrical Characteristics (@ T<sub>A</sub> = 25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
V <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250μA	-60	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = -60V, V <sub>GS</sub> = 0V	-	-	-1	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V	-	-	±10	μA
<b>On Characteristics</b>						
R <sub>DS(ON)</sub>	Drain-Source On-resistance <sup>*2</sup>	V <sub>GS</sub> = -10V, I <sub>D</sub> = -0.1A	-	1.8	4	Ω
		V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -0.1A	-	2.3	5	
V <sub>GS(TH)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250μA	-1	-1.5	-2	V
<b>Dynamic Characteristics</b>						
g <sub>fs</sub>	Transconductance	V <sub>DS</sub> = -10V, I <sub>D</sub> = -0.2A	-	0.5	-	S
C <sub>ISS</sub>	Input Capacitance	V <sub>GS</sub> = 0V V <sub>DS</sub> = -20V f = 1.0MHz	-	39	-	pF
C <sub>OSS</sub>	Output Capacitance		-	12	-	
C <sub>RSS</sub>	Reverse Transfer Capacitance		-	2	-	
<b>Switching Characteristics</b>						
t <sub>d(ON)</sub>	Turn-on Delay Time <sup>*4</sup>	V <sub>DS</sub> = -15V R <sub>L</sub> = -50Ω I <sub>D</sub> = -2.5A	-	2.5	-	ns
t <sub>r</sub>	Turn-on Rise Time <sup>*4</sup>		-	1	-	
t <sub>d(OFF)</sub>	Turn-Off Delay Time <sup>*4</sup>		-	16	-	
t <sub>f</sub>	Turn-Off Fall Time <sup>*4</sup>		-	8	-	
Q <sub>G</sub>	Total Gate-Charge	V <sub>DS</sub> = -25V	-	2	-	nC
Q <sub>GS</sub>	Gate to Source Charge	V <sub>GS</sub> = -4.5V	-	0.7	-	
Q <sub>GD</sub>	Gate to Drain (Miller) Charge	I <sub>D</sub> = -0.2A	-	0.5	-	
<b>Source-Drain Diode Characteristics</b>						
V <sub>SD</sub>	Diode Forward Voltage <sup>*2</sup>	I <sub>S</sub> = -0.2A, V <sub>GS</sub> = 0 V	-	-0.87	-1.4	V

Notes:

- The data tested by surface mounted on a minimum recommended pad
- The data tested by pulsed, pulse width ≤ 300μs, duty cycle ≤ 2%
- The E<sub>AS</sub> data shows Max. rating. The test condition is V<sub>DD</sub> = -30V, V<sub>GS</sub> = -10V, L = 0.1mH
- Guaranteed by design, not subject to production

Ratings and Characteristics Curves (@  $T_A = 25^\circ\text{C}$  unless otherwise specified)

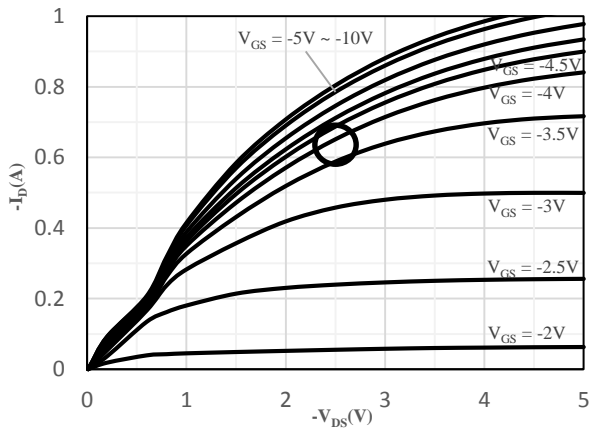


Fig 1 Typical Output Characteristics

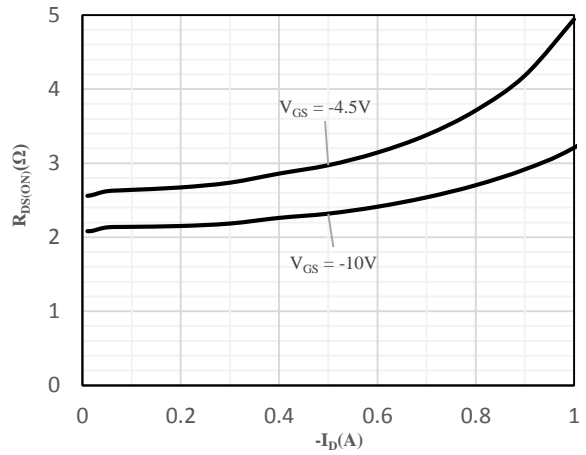


Fig 2 On-Resistance vs. Drain Current and Gate Voltage

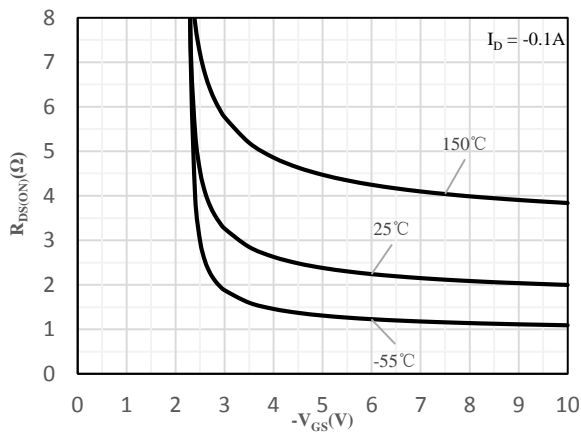


Fig 3 On-Resistance vs. Gate-Source Voltage

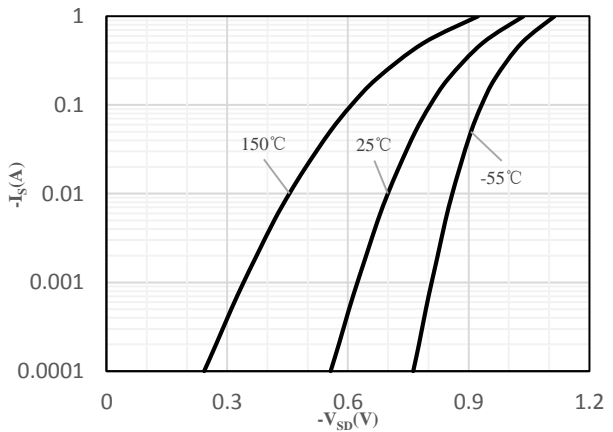


Fig 4 Body-Diode Characteristics

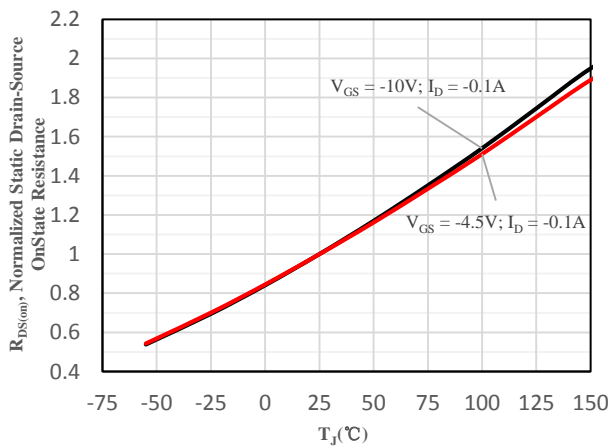


Fig 5 Normalized On-Resistance vs. Junction Temperature

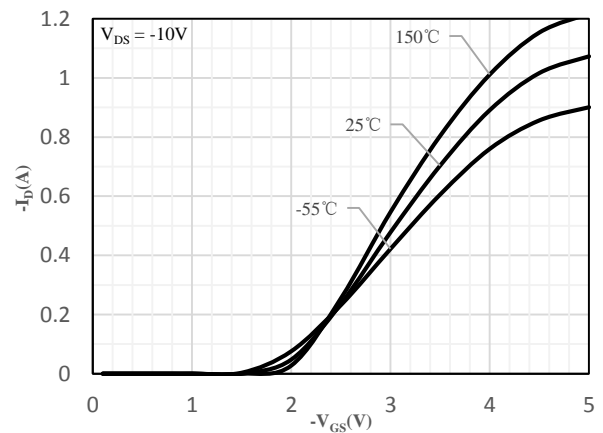


Fig 6 Transfer Characteristics

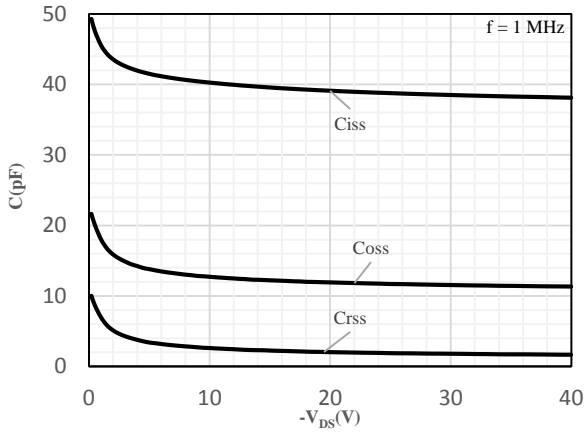


Fig 7 Capacitance Characteristics

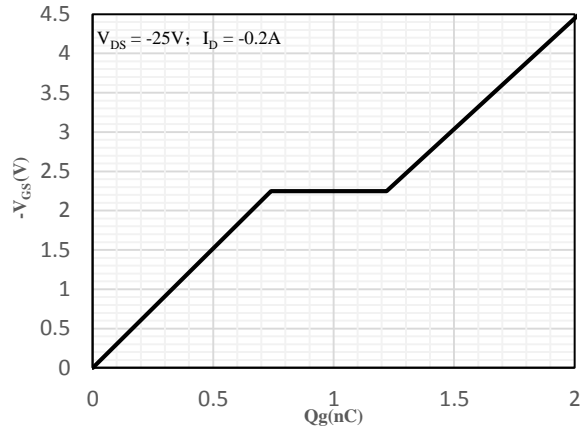


Fig 8 Gate-Charge Characteristics

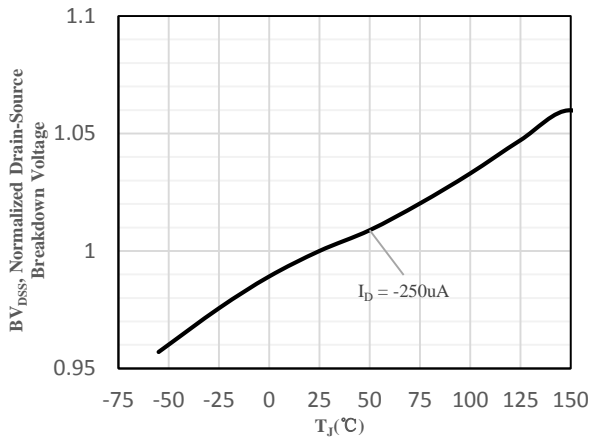


Fig 9 Normalized Breakdown Voltage vs. Junction Temperature

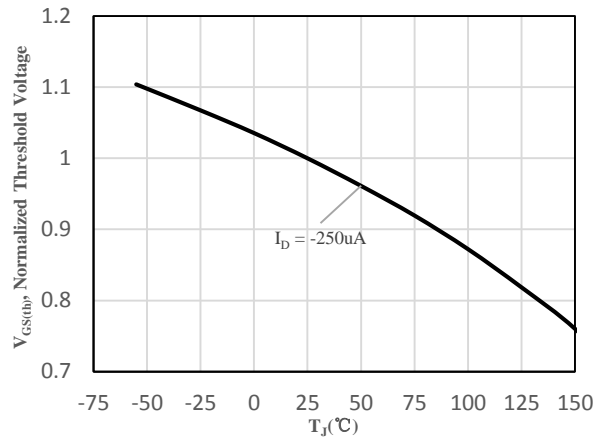


Fig 10 Normalized  $V_{GS(th)}$  vs. Junction Temperature

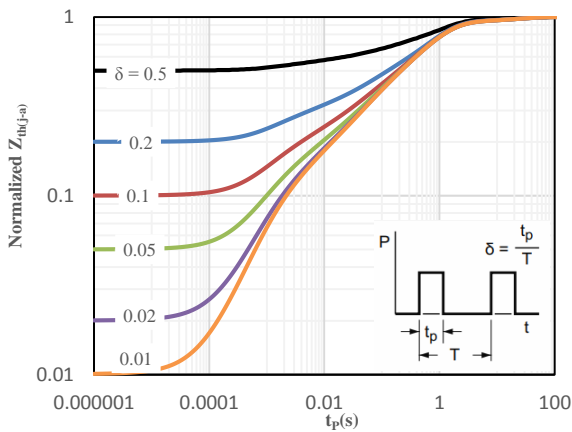
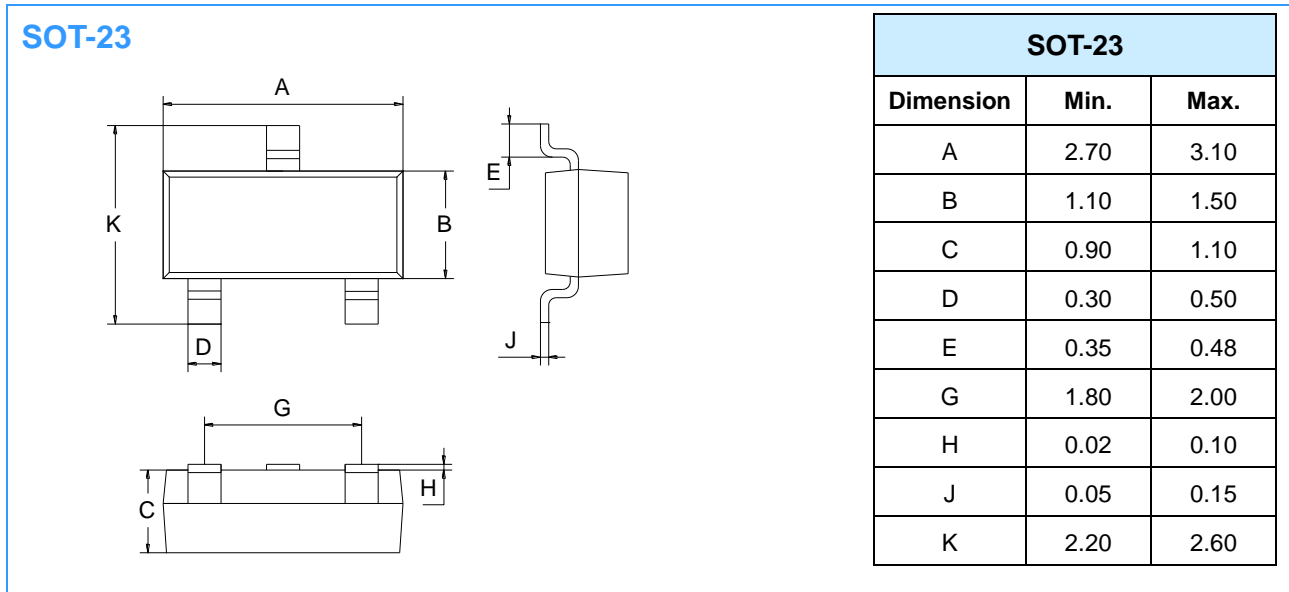
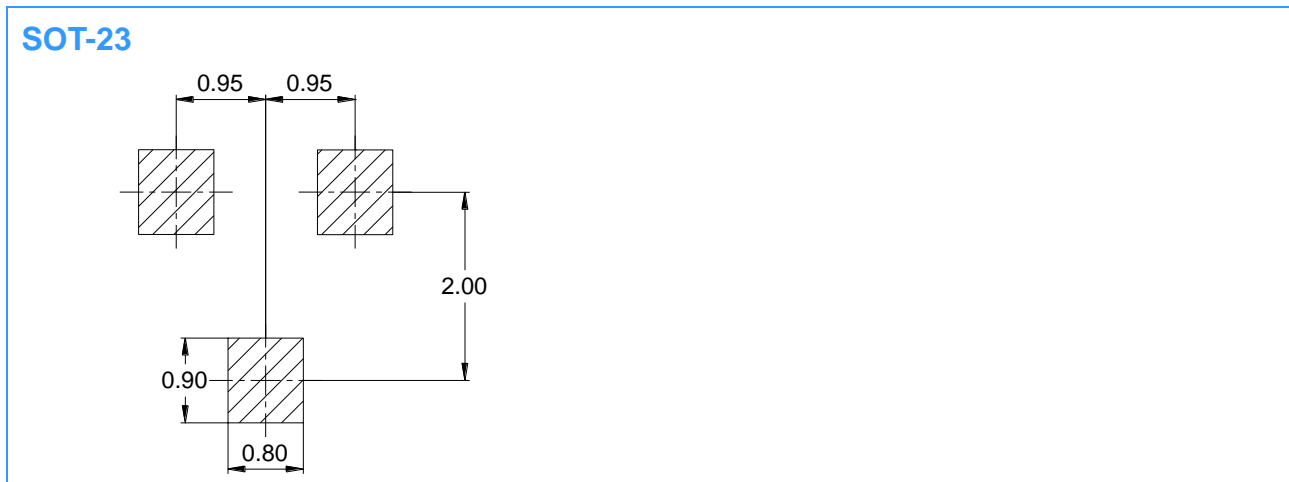


Fig 11 Normalized Maximum transient thermal impedance

**Package Outline Dimensions** (Unit: mm)



**Mounting Pad Layout** (Unit: mm)



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